Product Change Notification - RMES-24DZDY117

Date:

26 Jun 2019

Product Category:

Ethernet Switches

Affected CPNs:

Notification subject:

CCB 3847 Initial Notice: Qualification of GTK as a new assembly site for selected Micrel products of the 0.11 um wafer technology at DBHU available in 64L LQFP (10x10x1.4mm) package

Notification text:

PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of GTK as a new assembly site for selected Micrel products of the 0.11 um wafer technology at DBHU available in 64L LQFP (10x10x1.4mm) package.

Pre Change:

Assembled at TICP using CEL-9200 mold compound material

Post Change:

Assembled at GTK using G700H mold compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Taiwan IC Packing Corp (TICP)	GREATEK ELETRONIC INC. (GTK)
Wire material	Au	Au
Die attach material	EN4900	EN4900
Molding compound material	CEL-9200	G700H
Lead frame material	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying GTK as a new assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

September 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	June 2019					->	September 2019				
Workweek	22	23	24	25	26		31	32	33	34	35
Initial PCN Issue Date					X						
Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

June 26, 2019: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_RMES-24DZDY117_Qual_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

KSZ8852HLEWA
KSZ8852HLEYA